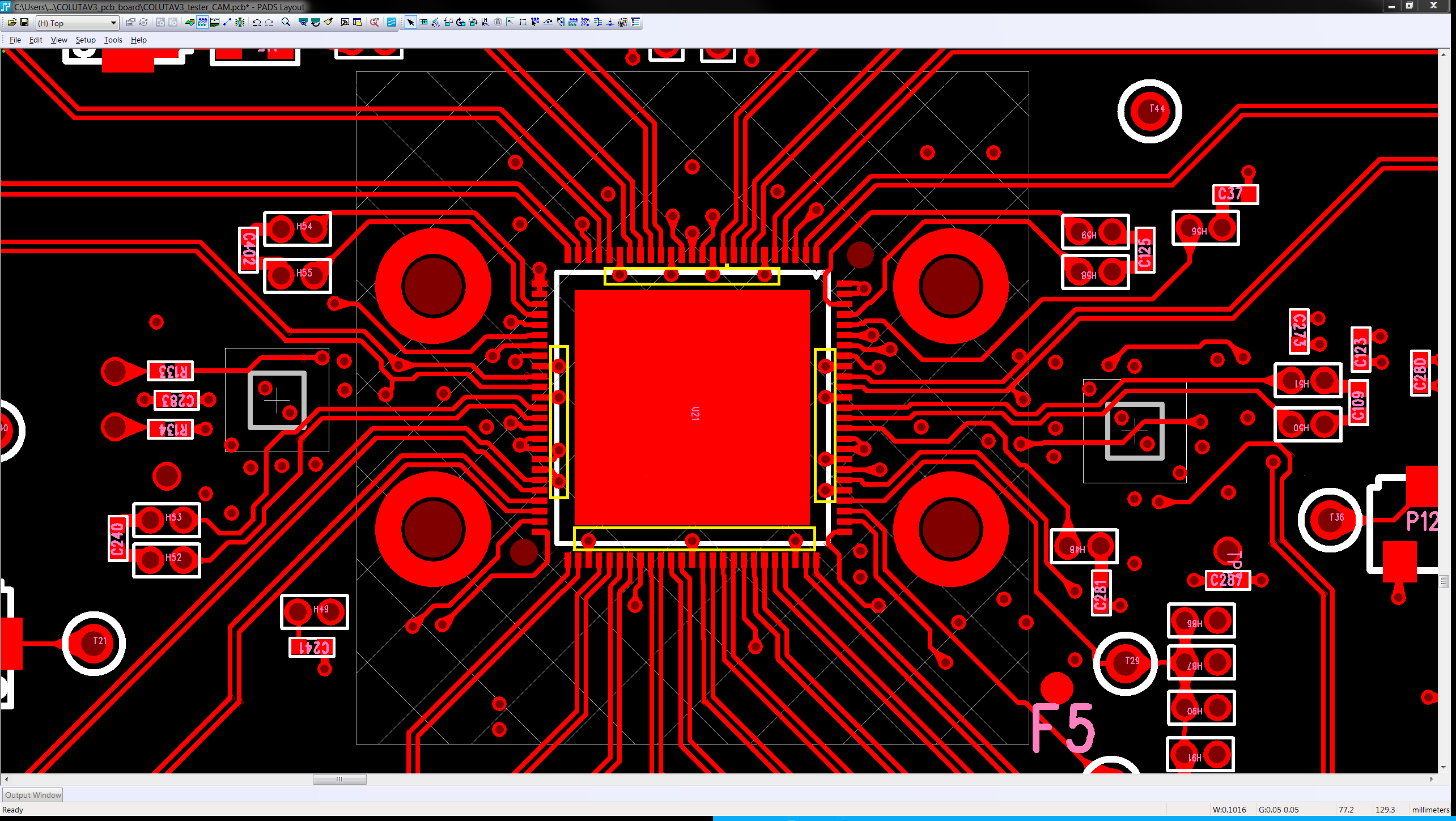
Dears,

We use the socket for 100pin, 0.4mm QFN socket (Plastronix part 100QHC40A21212).



A/

Please, put solder mask on vias in the yellow boxes (15 vias in total).

Apply this for top layer. The reason is that instead of the socket we may need to solder on the same place the chip. The chip has (almost) the same pin padstack as the socket. The difference is chip bottom pad which is larger for the chip.

B/

The PCB pad plating should be 30uin hard au 0ver 300uin Ni over 1oz min Cu.

Contact plating should be 300uin Au over 75uin Ni.